

AMENDMENTS TO THE CLAIMS:

Please amend claims 31, 32, 42 and 43, as shown below.

This listing of claims will replace all prior versions and listings of claims in the
Application:

Claims 1-30 (canceled)

Claim 31 (currently amended): A semiconductor device comprising:

a first transistor which is connected between a first power supply line and a first node
and has a gate that is connected to a second node without connection to a first node;

a second transistor which is connected between a second power supply line and said
second node and has a gate that is connected to a first node without connection to said second
node;

an extended gate wiring that is extended from the gate electrode of said first transistor
up to the vicinity of a diffusion layer of said second transistor; and

a common contact formed across the extended gate wiring and the diffusion layer of
said second transistor,

said transistor comprising:

a semiconductor substrate;

a gate insulation film formed on said semiconductor substrate;

a gate electrode formed on said gate insulation film and having a portion increasing
upward in the length along a gate length direction, said gate electrode further having a visor
portion; and

a side wall formed on a side surface of said gate electrode so as to be covered behind
[[a]] said visor portion of said gate electrode[[;]],

~~an interlayer insulation film covering said gate electrode; and~~
~~a contact formed in said interlayer insulation film and being in contact with a top~~
~~surface and a side surface of said visor portion, said side wall and said diffusion layer a silicide~~
~~film formed on a top surface of said semiconductor substrate;~~

wherein said visor portion has no overhang with respect to said side wall.

Claim 32 (currently amended): A semiconductor device comprising:

a first transistor which is connected between a first power supply line and a first node
and has a gate that is connected to a second node without connection to a first node;

a second transistor which is connected between a second power supply line and said
second node and has a gate that is connected to a first node without connection to said second
node;

an extended gate wiring that is extended from the gate electrode of said first transistor
up to the vicinity of a diffusion layer of said second transistor; and

a common contact formed across the extended gate wiring and the diffusion layer of
said second transistor.

said transistor comprising:

a semiconductor substrate;

a gate insulation film formed on said semiconductor substrate;

a gate electrode formed on said gate insulation film and having a portion increasing
upward in the length along a gate length direction, said gate electrode further having a visor
portion; and

a side wall formed on a side surface of said gate electrode so as to be covered behind
[[a]] said visor portion of said gate electrode, said side wall being formed of a lamination of at
least two insulation films having different etching properties,

wherein said visor portion has no overhang with respect to said side wall.[:]] and

~~a contact formed in said interlayer insulation film and being in contact with a top
surface and a side surface of said visor portion, said side wall and said diffusion layer a silicide
film formed on a top surface of said semiconductor substrate.~~

Claim 33 (canceled)

Claim 34 (previously presented): The semiconductor device according to claim 31,
wherein said gate electrode comprises a lower part substantially constant in the length along
said gate length direction, and an upper part on said lower part increasing upward in the length
along said gate length direction.

Claim 35 (previously presented): The semiconductor device according to claim 32,
wherein said gate electrode comprises a lower part substantially constant in the length along
said gate length direction, and an upper part on said lower part increasing upward in the length
along said gate length direction.

Claim 36 (canceled)

Claim 37 (previously presented): The semiconductor device according to claim 34,
wherein said side wall is formed on both a side surface of said upper part and a side surface of
said lower part.

Claim 38 (previously presented): The semiconductor device according to claim 35,
wherein said side wall is formed on both a side surface of said upper part and a side surface of
said lower part.

Claim 39 (canceled)

Claim 40 (previously presented): The semiconductor device according to claim 37, wherein a side surface of said upper part forms a tapered slope.

Claim 41 (previously presented): The semiconductor device according to claim 38, wherein a side surface of said upper part forms a tapered slope.

Claim 42 (currently amended): The semiconductor device according to claim 31, wherein ~~said gate electrode is a gate electrode of one transistor and~~ said diffusion layer is also a diffusion layer of a drain or source of ~~another~~ a third transistor.

Claim 43 (currently amended): The semiconductor device according to claim 32, wherein ~~said gate electrode is a gate electrode of one transistor and~~ said diffusion layer is also a diffusion layer of a drain or source of ~~another~~ a third transistor.

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